



Material Content Data Sheet



Sales Product Name		IDD15E60		Issued		19. July 2018		
MA#		MA000081271						
Package		PG-TO252-3-11		Weight*		364.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.385	0.38	0.38	3801	3801
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		591	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		177	
	non noble metal	copper	7440-50-8	215.017	59.02	59.10	590271	591039
wire	non noble metal	aluminium	7429-90-5	1.021	0.28	0.28	2802	2802
encapsulation	organic material	carbon black	1333-86-4	1.221	0.34		3352	
	inorganic material	antimonytrioxide	1309-64-4	2.442	0.67		6704	
	plastics	brominated resin	-	2.442	0.67		6704	
	plastics	epoxy resin	-	24.419	6.70		67035	
	inorganic material	silicondioxide	60676-86-0	91.571	25.14	33.52	251383	335178
leadfinish	non noble metal	tin	7440-31-5	3.740	1.03	1.03	10267	10267
plating	non noble metal	nickel	7440-02-0	0.091	0.02		249	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	250
solder	noble metal	silver	7440-22-4	0.036	0.01		99	
	non noble metal	tin	7440-31-5	0.029	0.01		79	
	non noble metal	lead	7439-92-1	1.373	0.38	0.40	3770	3948
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		53	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	copper	7440-50-8	19.177	5.26	5.27	52646	52715
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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